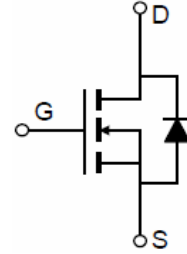


## N-Channel Super Trench Power MOSFET

### Description

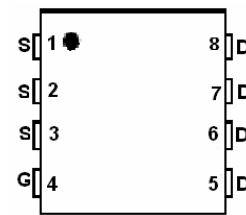
The RM150N60DF uses **Super Trench** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of  $R_{DS(on)}$  and  $Q_g$ . This device is ideal for high-frequency switching and synchronous rectification.



Schematic diagram

### General Features

- $V_{DS} = 60V, I_D = 150A$
- $R_{DS(on)} < 2.3m\Omega @ V_{GS} = 10V$  (TYP:  $1.9m\Omega$ )
- $R_{DS(on)} < 3.5m\Omega @ V_{GS} = 4.5V$  (TYP:  $3.0m\Omega$ )
- Excellent gate charge x  $R_{DS(on)}$  product
- Very low on-resistance  $R_{DS(on)}$
- 150 °C operating temperature
- Pb-free lead plating
- 100% UIS tested

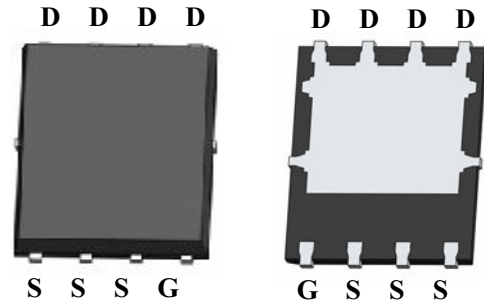


Marking and pin assignment

### Application

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification
- Halogen-free

**100% UIS TESTED!**  
**100%  $\Delta V_{ds}$  TESTED!**



Top View

Bottom View

### Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
150N60	RM150N60DF	DFN5X6-8L	-	-	-

### Absolute Maximum Ratings ( $T_C = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current ( $T_a = 25^\circ C$ )	$I_D$	150	A
Continuous Drain Current ( $T_a = 100^\circ C$ )	$I_D$	100	A
Pulsed Drain Current <sup>(1)</sup>	$I_{DM}$	450	A
Single Pulsed Avalanche Energy <sup>(2)</sup>	$E_{AS}$	520	mJ
Power Dissipation	$P_D$	140	W
Thermal Resistance from Junction to Case	$R_{\theta JC}$	0.89	$^\circ C/W$
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	45	$^\circ C/W$
Junction Temperature	$T_J$	150	$^\circ C$
Storage Temperature	$T_{STG}$	-55~ +150	$^\circ C$

## Electrical Characteristics (T<sub>c</sub>=25°C unless otherwise noted)

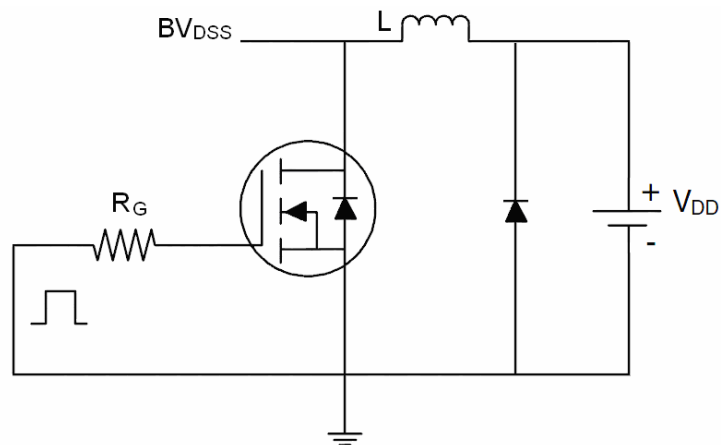
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
<b>Static Characteristics</b>						
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	60	-	-	V
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 60V, V <sub>GS</sub> = 0V	-	-	1	μA
Gate-body leakage current	I <sub>GSS</sub>	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V	-	-	±100	nA
Gate threshold voltage <sup>(3)</sup>	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	1.5	2.0	3.0	V
Drain-source on-resistance <sup>(3)</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 20A	-	1.9	2.3	mΩ
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 10A	-	3.0	3.5	mΩ
Forward Threshold Voltage	g <sub>fs</sub>	V <sub>DS</sub> = 5V, I <sub>D</sub> = 20A	-	75	-	S
<b>Dynamic characteristics</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 25V, V <sub>GS</sub> = 0V, f = 100KHz	-	6052	-	pF
Output Capacitance	C <sub>oss</sub>		-	1470	-	
Reverse Transfer Capacitance	C <sub>rss</sub>		-	185	-	
<b>Switching characteristics</b>						
Turn-on delay time	t <sub>d(on)</sub>	V <sub>DD</sub> = 30V, I <sub>D</sub> = 25A, V <sub>GS</sub> = 10V, R <sub>G</sub> = 2Ω	-	8	-	ns
Turn-on rise time	t <sub>r</sub>		-	15	-	
Turn-off delay time	t <sub>d(off)</sub>		-	55	-	
Turn-off fall time	t <sub>f</sub>		-	25	-	
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> = 30V, I <sub>D</sub> = 25A, V <sub>GS</sub> = 10V	-	110	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	20	-	
Gate-Drain Charge	Q <sub>gd</sub>		-	21	-	
Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> = 20A, di/dt = 100A/us		100		nC
Reverse Recovery Time	T <sub>rr</sub>	I <sub>F</sub> = 20A, di/dt = 100A/us		72		ns
<b>Source-Drain Diode characteristics</b>						
Diode Forward voltage <sup>(3)</sup>	V <sub>SD</sub>	V <sub>GS</sub> = 0V, I <sub>S</sub> = 10A	-	-	1.2	V
Diode Forward current <sup>(4)</sup>	I <sub>S</sub>		-	-	150	A

### Notes:

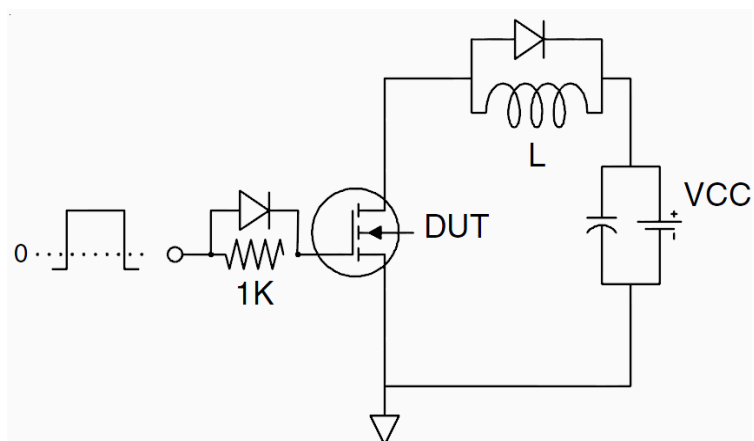
1. Repetitive Rating: pulse width limited by maximum junction temperature
2. EAS Condition: T<sub>J</sub> = 25°C, V<sub>DD</sub> = 48V, R<sub>G</sub> = 25 Ω, L = 0.5Mh
3. Pulse Test: pulse width ≤ 300μs, duty cycle ≤ 2%
4. Surface Mounted on FR4 Board, t ≤ 10 sec

## Test Circuit

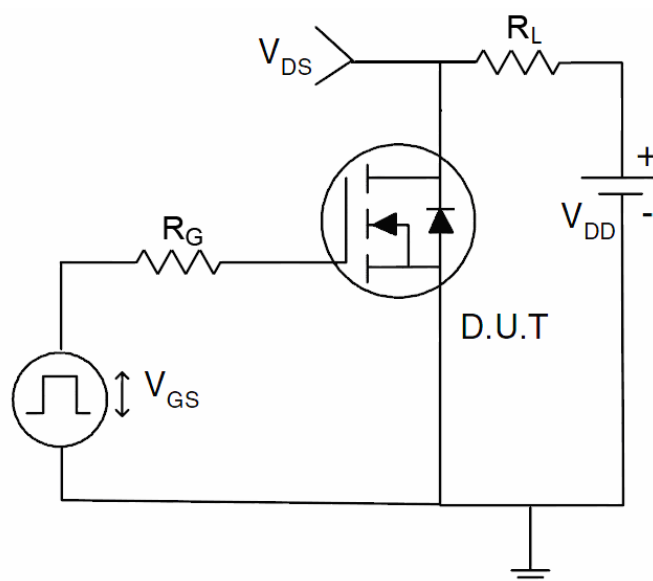
### 1) $E_{AS}$ test Circuit



### 2) Gate charge test Circuit



### 3) Switch Time Test Circuit



## RATING AND CHARACTERISTICS CURVES (RM150N60DF)

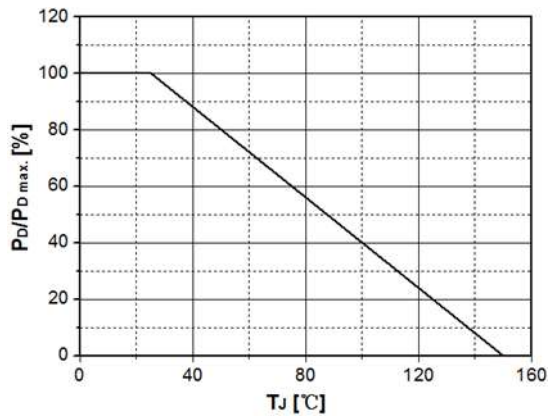


Fig.1 Power Dissipation Derating Curve

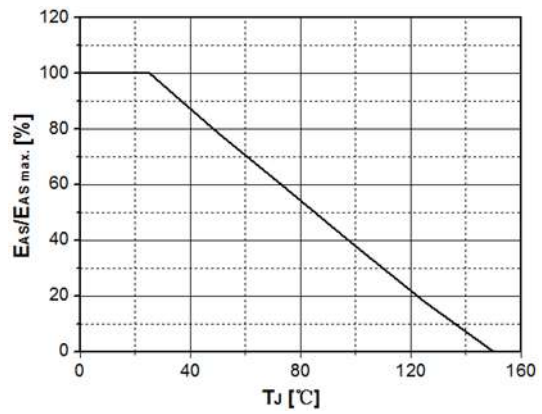


Fig.2 Avalanche Energy Derating Curve vs. Junction Temperature

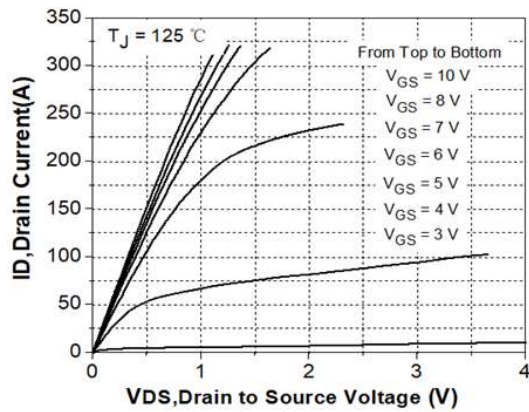


Fig.3 Typical Output Characteristics

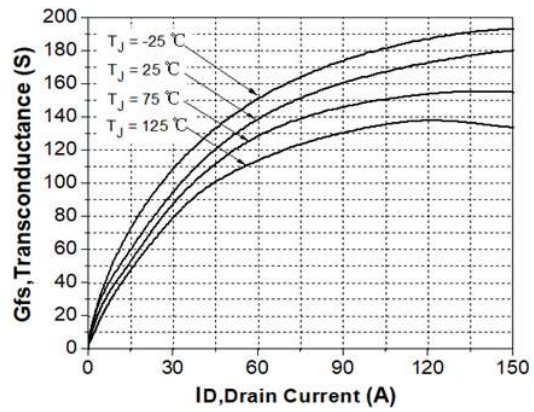


Fig. 4 Transconductance vs. Drain Current

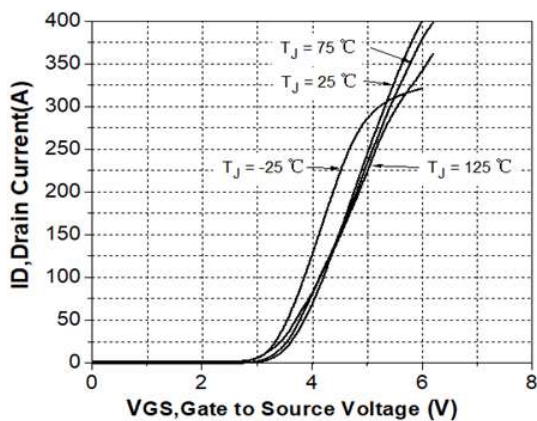


Fig.5 Typical Transfer Characteristics

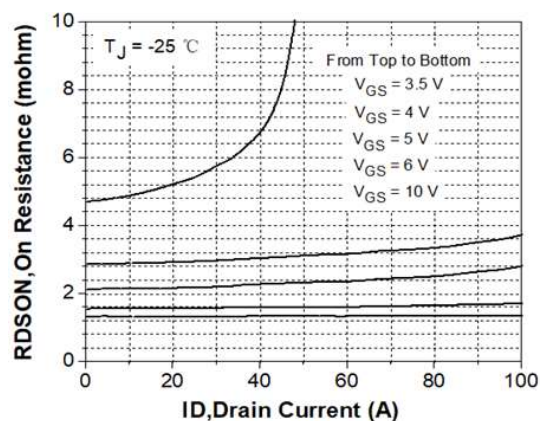


Fig. 6 State Resistance vs. Drain Current @ -25°C

## RATING AND CHARACTERISTICS CURVES (RM150N60DF)

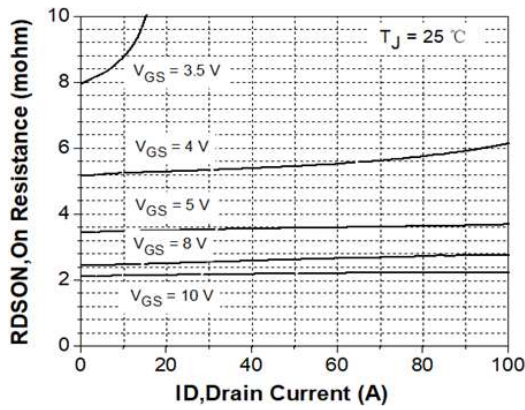


Fig.7 State Resistance vs. Drain Current @25°C

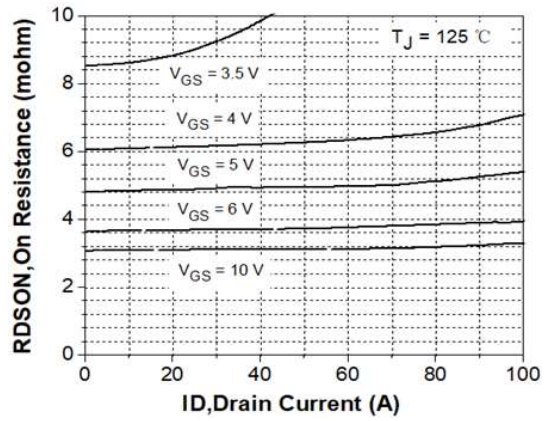


Fig. 8 State Resistance vs. Drain Current @125°C

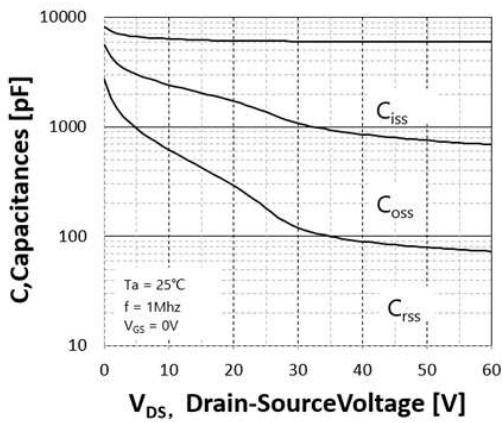


Fig.9 Typical Capacitance vs. Drain Source Voltage

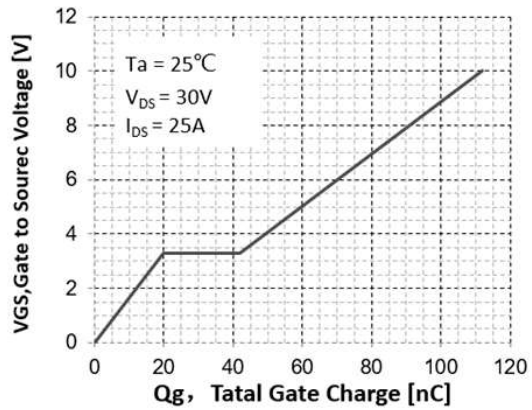


Fig.10 Dynamic Input Characteristics

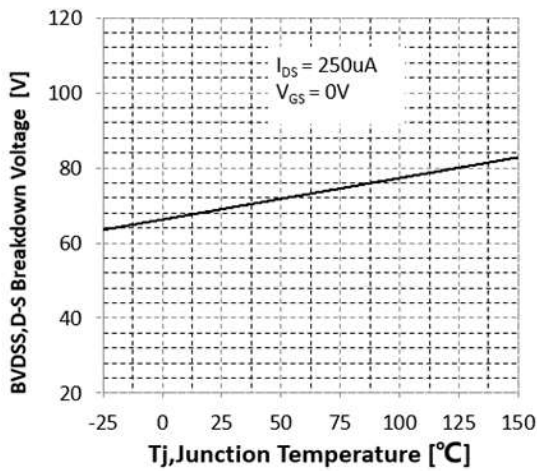


Fig.11 Breakdown Voltage vs. Junction Temperature

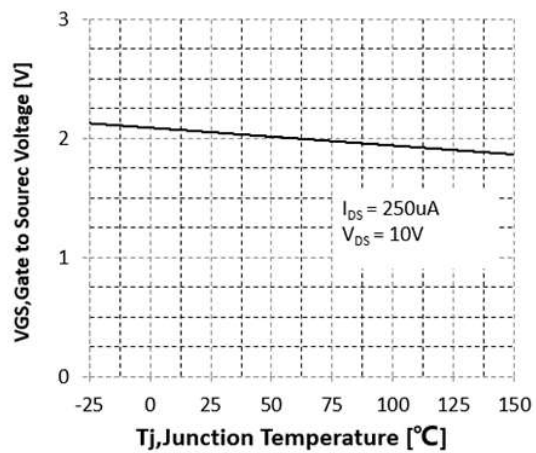
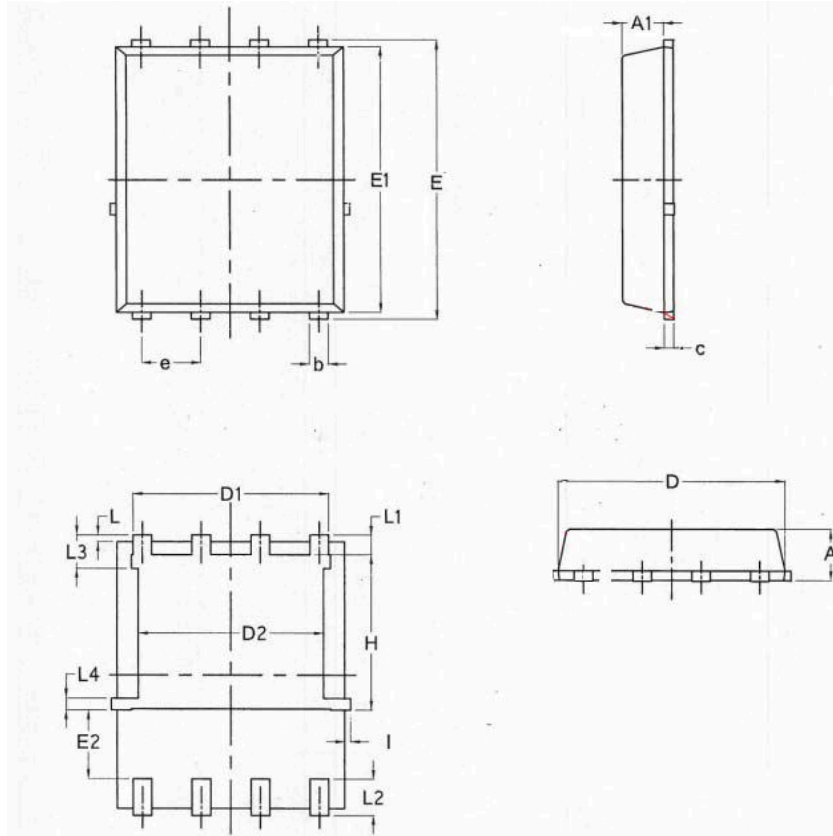


Fig. 12 Gate Threshold Voltage vs. Junction Temperature



## DFN5X6-8L Package Information



Symbol	Dimensions In Millimeters			Dimensions In Inches		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	0.90	1.10	1.17	0.0354	0.0433	0.0461
A1	0.824	0.897	0.97	0.0324	0.0353	0.0382
b	0.33	0.41	0.50	0.0130	0.0161	0.0197
C	0.150	0.20	0.250	0.0059	0.0079	0.0098
D	4.80	4.90	5.00	0.1890	0.1929	0.1969
D1	3.91	4.22	4.36	0.1539	0.1661	0.1717
D2	3.85	4.00	4.15	0.1516	0.1575	0.1634
E	5.90	6.05	6.15	0.2323	0.2382	0.2421
E1	5.65	5.76	5.85	0.2224	0.2268	0.2303
E2	1.10	/	/	0.0433	/	/
e	1.27 BSC			0.050 BSC		
L	0.05	0.15	0.25	0.0020	0.0059	0.0098
L1	0.38	0.425	0.50	0.0150	0.0167	0.0197
L2	0.51	0.785	0.86	0.0201	0.0309	0.0339
L3	0.55	0.70	0.85	0.0217	0.0276	0.0335
L4	0.10	0.25	0.40	0.0039	0.0098	0.0157
H	3.25	3.35	3.58	0.1280	0.1319	0.1409
I	0	/	0.18	0	/	0.0071

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